

## N-Ch 100V Fast Switching MOSFETs

### Features:

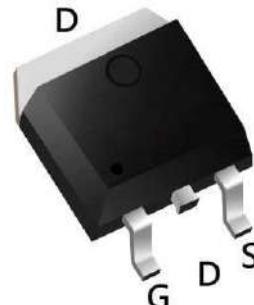
- ★ Advanced Trench MOS Technology
- ★ 100% EAS Guaranteed
- ★ Super Low RDS(ON)
- ★ Green Device Available

### Applications:

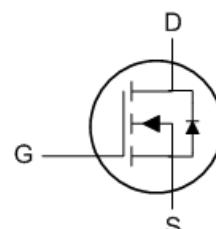
- ★ MOTOR Driver.
- ★ BMS.
- ★ High frequency switching and synchronous rectification.

### Product Summary

BVDSS	RDS <sub>ON</sub>	ID
100V	4.5mΩ	120A



**TO263 Pin Configuration**



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	120	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	100	A
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	15.6	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	12.4	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	480	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	702	mJ
I <sub>AS</sub>	Avalanche Current	53	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	250	W
P <sub>D</sub> @T <sub>C</sub> =100°C	Total Power Dissipation <sup>4</sup>	100	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	2.0	W
P <sub>D</sub> @T <sub>A</sub> =70°C	Total Power Dissipation <sup>4</sup>	1.3	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	0.5	°C/W

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	100	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=30\text{A}$	---	3.7	4.5	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	2.0	3.0	4.0	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^{\circ}\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^{\circ}\text{C}$	---	---	10	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_{\text{D}}=30\text{A}$	---	50	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1	---	$\Omega$
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=20\text{A}$	---	72	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	28	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	15	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_g=3.0\Omega$ , $I_{\text{D}}=20\text{A}$	---	35	---	$\text{ns}$
$T_r$	Rise Time		---	18	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	45	---	
$T_f$	Fall Time		---	55	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	4725	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	609	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	14	---	

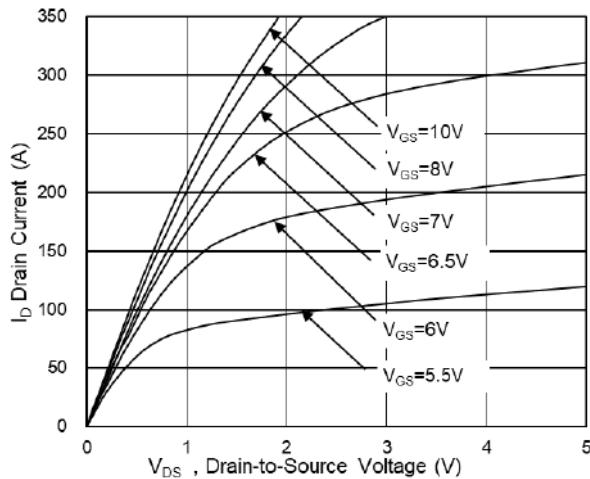
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	120	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=50\text{A}$ , $T_J=25^{\circ}\text{C}$	---	---	1.3	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=30\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^{\circ}\text{C}$	---	70	---	nS
			---	170	---	nC

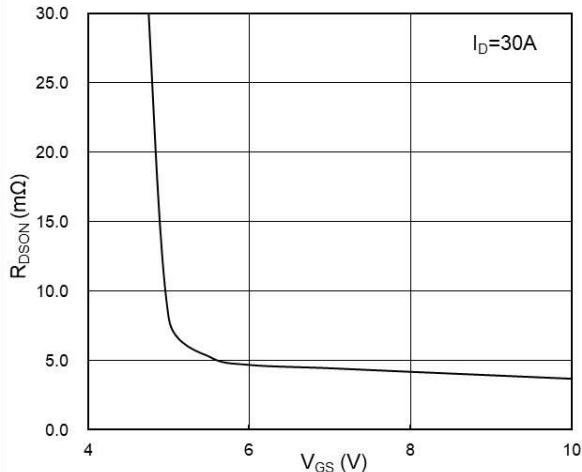
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $I_{\text{AS}}=53\text{A}$
- 4.The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.
- 6.Package limitation current.

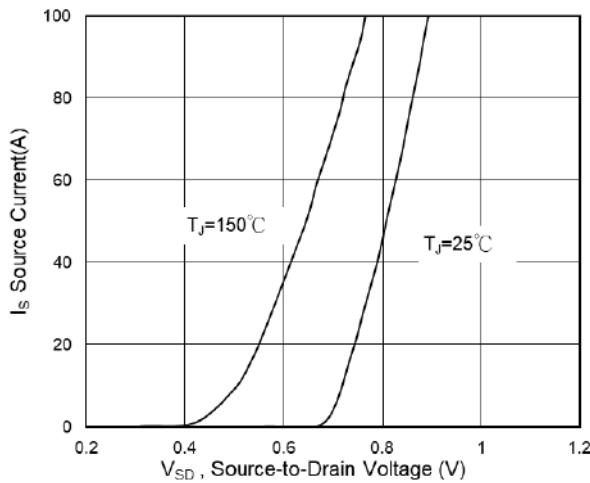
### Typical Characteristics



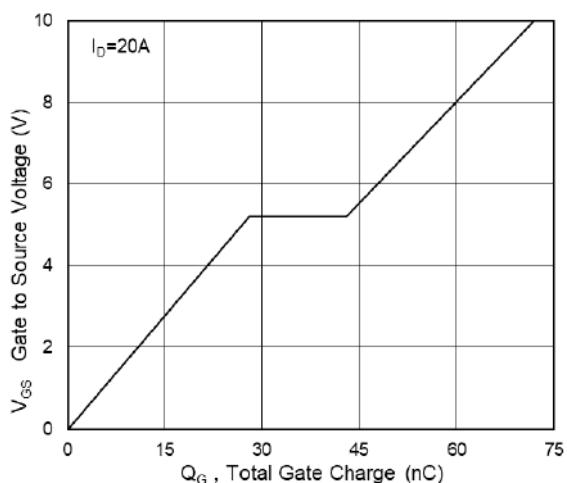
**Fig.1 Typical Output Characteristics**



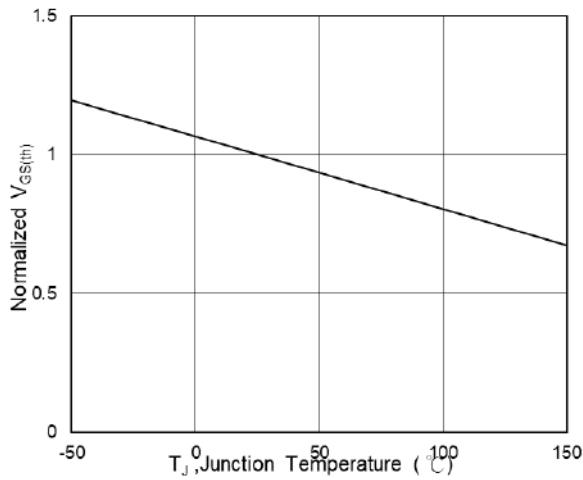
**Fig.2 On-Resistance vs G-S Voltage**



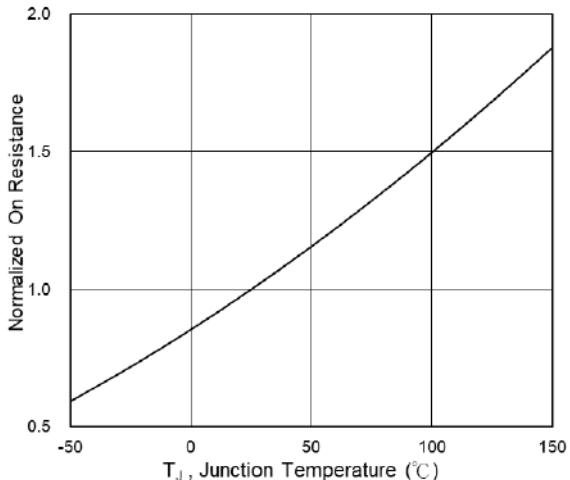
**Fig.3 Source Drain Forward Characteristics**



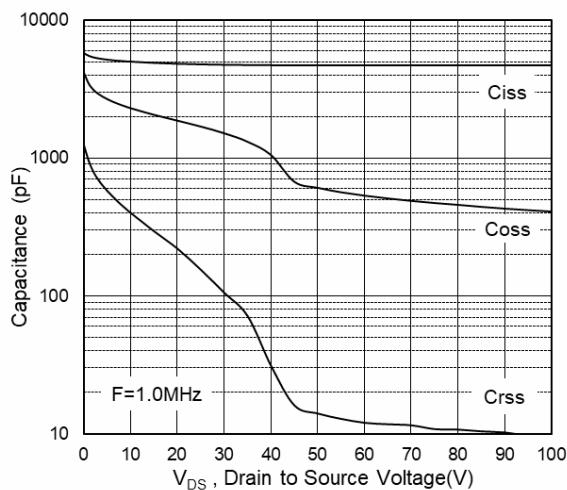
**Fig.4 Gate-Charge Characteristics**



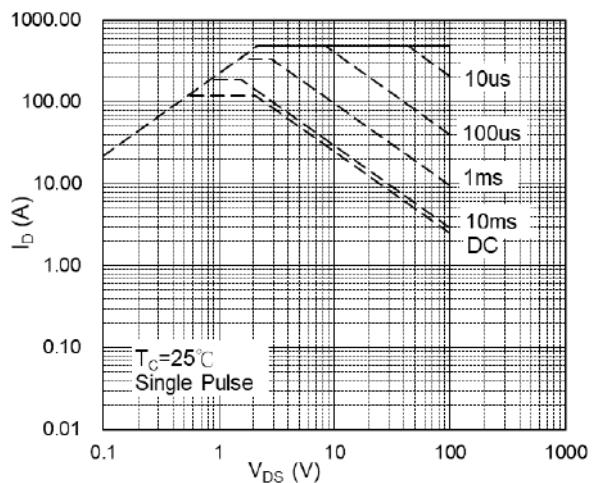
**Fig.5 Normalized  $V_{TH}$  vs  $T_J$**



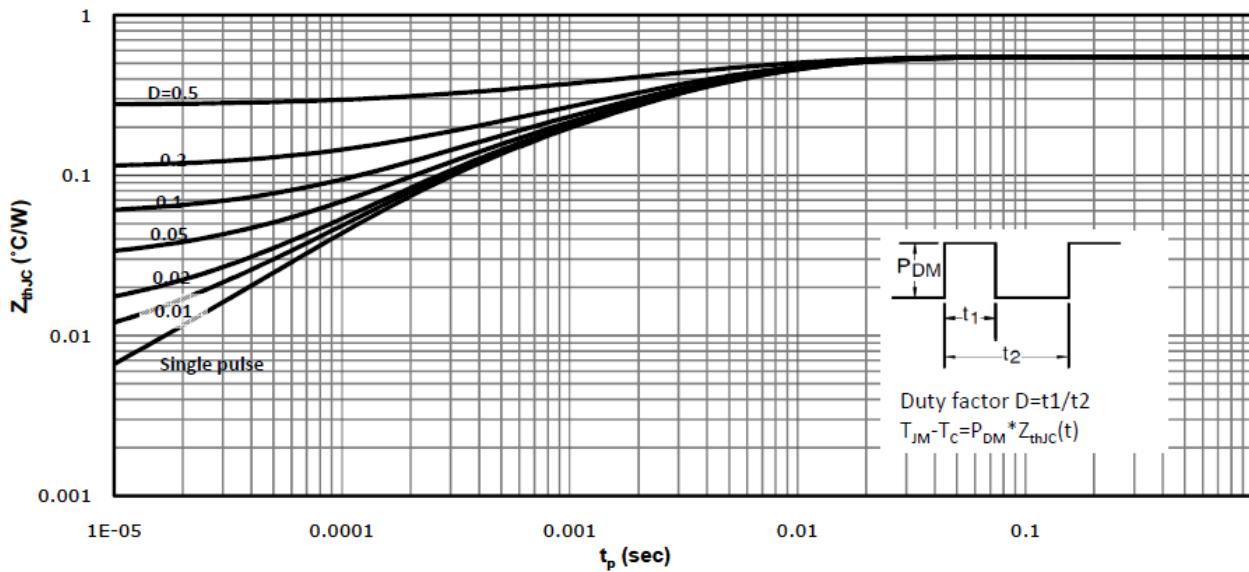
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



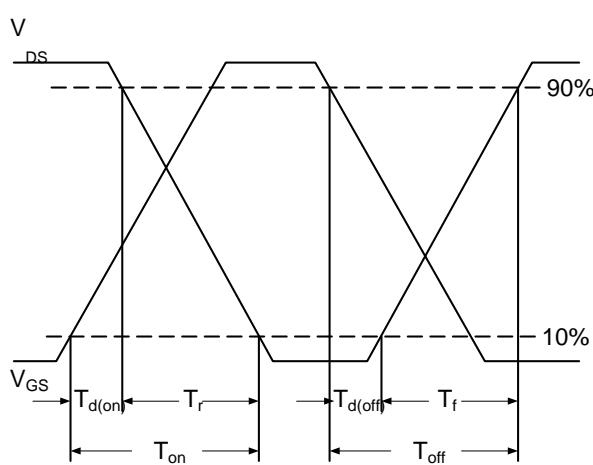
**Fig.7 Capacitance**



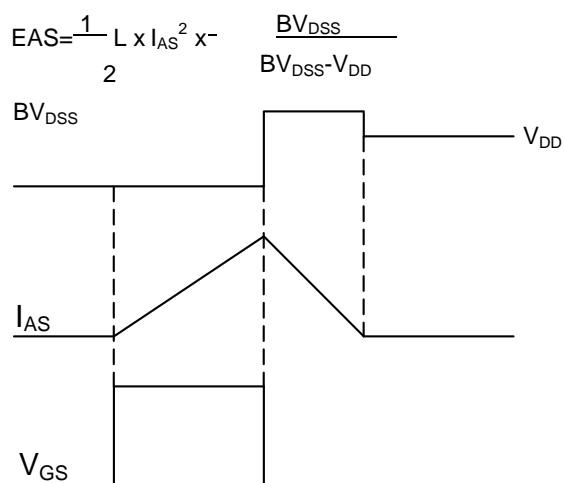
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**